

Title (en)  
Copper alloy and method of manufacturing the same

Title (de)  
Kupferlegierung und Verfahren zu deren Herstellung

Title (fr)  
Alliage de cuivre et procédé pour sa fabrication

Publication  
**EP 1630239 B1 20071017 (EN)**

Application  
**EP 05018715 A 20050829**

Priority  
JP 2004250938 A 20040830

Abstract (en)  
[origin: EP1630239A1] A copper alloy of superior flex durability is provided that is suitable for the conducting members of flexible printed circuits. This is a copper alloy where the integrated intensity ratio  $I\{200\} / I\{111\}$  found by x-ray diffraction of the rolled surface is 1.5 or less. Examples of its specific chemical composition are: a composition where, in percent by weight, Fe: 0.045-0.095%, P: 0.010-0.030%, the sum of all elements other than Fe, P and Cu is less than 1% and the balance is Cu, and a composition where, in percent by weight, Ni: 0.5-3.0%, Sn: 0.5-2.0%, P: 0.03-0.10%, the sum of all elements other than Ni, Sn, P and Cu is less than 1% and the balance is Cu. The copper alloy has a conductivity of 85% IACS or greater.

IPC 8 full level  
**C22C 9/00** (2006.01); **C22C 9/02** (2006.01); **C22C 9/06** (2006.01); **C22F 1/08** (2006.01)

CPC (source: EP US)  
**C22C 9/02** (2013.01 - EP US); **C22C 9/06** (2013.01 - EP US); **C22F 1/08** (2013.01 - EP US); **H05K 1/09** (2013.01 - EP US); **H05K 2201/0355** (2013.01 - EP US)

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